

To: NXP Manufacturing (Thailand) Ltd

Content of certain hazardous substances

We hereby confirm that the following hazardous substances listed on the attached sheet aren't used intentionally as ingredient(s) for the following product manufactured by Shin-Etsu Electronics (Malaysia) Sdn. Bhd. except for the substance(s) listed on the following page(s).

Moreover, the contents as impurities of RoHS substances don't exceed their threshold limits.

The analysis results of one optional lot are attached.

1. Product : KMC-184-8
2. Hazardous substance : Attached

This investigation is conducted only for the product itself.
Packing materials are out of scope of the investigation.



Takayuki Aoki
Managing Director
Shin-Etsu Electronics (Malaysia) Sdn. Bhd.

Investigation Result

Product	Contained Hazardous Substance	Content (%)
KMC-184-8	Bromine compounds	ca. 2
	Antimony compounds	ca. 2

Environmental Hazardous Substances

Substances		Threshold Limit (ppm)
Heavy metals	Cadmium and its compounds	100
	Lead and its compounds	1000
	Mercury and its compounds	1000
	Hexavalent chromium compounds	1000
Brominated organic compounds	Polybrominated biphenyls(PBB)	1000
	Polybrominated diphenylethers(PBDE)	1000
Bis (2-ethylhexyl) phthalate (DEHP)		1000
Butyl benzyl phthalate (BBP)		1000
Dibutyl phthalate (DBP)		1000
Diisobutyl phthalate (DIBP)		1000
Halogen and its compounds (F, Cl, Br, I except for above mentioned)		
Antimony and its compounds		
Beryllium and its compounds		